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Electronic Patent Application Submission
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Application ID: 10667227



Title of Invention:

SEMICONDUCTOR PACKAGE AND
METHOD OF MAKING
LEADFRAME HAVING LEAD
LOCKS TO SECURE LEADS TO
ENCAPSULANT

First Named Inventor: Jae Yee

Domestic/Foreign Application: Domestic Application

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Statement

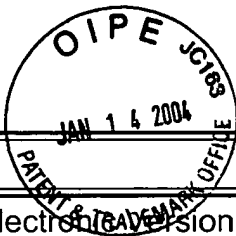
Filing Type:

Confirmation number: 7012

Attorney Docket Number: AMKOR012G1


Total Fees Authorized:

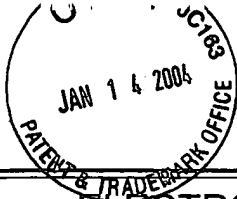
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**TRANSMITTAL**

Electronic Submission v1.1

Stylesheet Version v1.1.0

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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
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Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

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17	6239367	2001-05-29	HSUAN ET AL.
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24	6285075	2001-09-04	COMBS ET AL.
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26	6291271	2001-09-18	LEE ET AL.
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29	6297548	2001-10-02	MODEN ET AL.
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31	6303997	2001-10-16	LEE
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33	6307272	2001-10-23	TAKAHASHI ET AL.
34	6309909	2001-10-30	OHGIYAMA
35	6316838	2001-11-13	OZAWA ET AL.
36	6316822	2001-11-13	VENKATESHWARAN ET AL.
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39	6326244	2001-12-04	BROOKS ET AL.
40	6326243	2001-12-04	SUZUYA ET AL.
41	6335564	2002-01-01	POUR
42	6337510	2002-01-08	CHUN-JEN ET AL.
43	6339255	2002-01-15	SHIN
44	6348726	2002-02-19	BAYAN ET AL.

	45	6355502	2002-03-12	KANG ET AL.
	46	6369454	2002-04-09	CHUNG
	47	6369447	2002-04-09	MORI
	48	6373127	2002-04-16	BAUDOUIN ET AL.
	49	6380048	2002-04-30	BOON ET AL.
	50	6384472	2002-05-07	HUANG

Signature

Examiner Name	Date